

ABSTRACT

Extension of a crack occurring in a thermal storage layer and a protection film is suppressed. A thermal head (X1) of the invention includes a substrate (7), a thermal storage layer (13) disposed on one main surface of the substrate (7) so as to extend to an edge (7a) of the substrate (7), the thermal storage layer (13) being formed of glass; electrodes disposed on or above the thermal storage layer (13) apart from the edge (7a) of the substrate (7); heat-generating resistors (9) disposed above the thermal storage layer (13) apart from the edge (7a) of the substrate (7), the heat-generating resistors (9) being connected to the electrodes; a first covering layer (24) disposed on or above the electrodes and the heat-generating resistors (9); and a protection film (25) disposed on or above the first covering layer (24). The first covering layer (24) extends from atop the electrodes and the heat-generating resistors (9) toward atop the thermal storage layer (13) on the edge (7a) of the substrate (7), and the protection film (25) is disposed on or above the first covering layer (24) disposed on or above the electrodes and the heat-generating resistors (9) and an edge (25a) of the protection film (25) is not disposed above the edge (7a) of the substrate (7).